PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data			
1.1 Company		STMicroelectronics International N.V	
1.2 PCN No.		ADG/22/13572	
1.3 Title of PCN		L99PM62GXP / L99PM62GXPTR (UK19, ST Singapore Fab): Package Bill Of Material Upgrade	
1.4 Product Category		L99PM62GXP / L99PM62GXPTR (Singapore silicon Fab)	
1.5 Issue date		2022-07-26	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	KRISZTINA NEMETH	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Francesco MACINA	
2.1.2 Marketing Manager	Giovanni Luca TORRISI	
2.1.3 Quality Manager	Marcello Donato MENCHISE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ST Muar - Malaysia

4. Description of change		
	Old	New
4.1 Description	Au wires 1.3 mils Mold compound Hitachi CEL 9240	Cu wires 1.2mils Mold compound Sumitomo G700LS Leadframe finishing in rough copper
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change		
5.1 Motivation	Company Roadmap and Quality Improvement	
5.2 Customer Benefit	QUALITY IMPROVEMENT	

6. Marking of parts / traceability of change		
6.1 Description	Dedicated Finished Good Codes	

7. Timing / schedule		
7.1 Date of qualification results	2022-07-14	
7.2 Intended start of delivery	2022-11-01	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description	13572 Validation.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-07-26

9. Attachments (additional documentations)

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No	
	L99PM62GXPTR		

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